



SOT1161-1

plastic, extremely thin quad flat package; no leads; 16 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN16
Package type industry code	XQFN16
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	29-12-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.7	-	1.8	1.9	mm
E	package width	2.5	-	2.6	2.7	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	

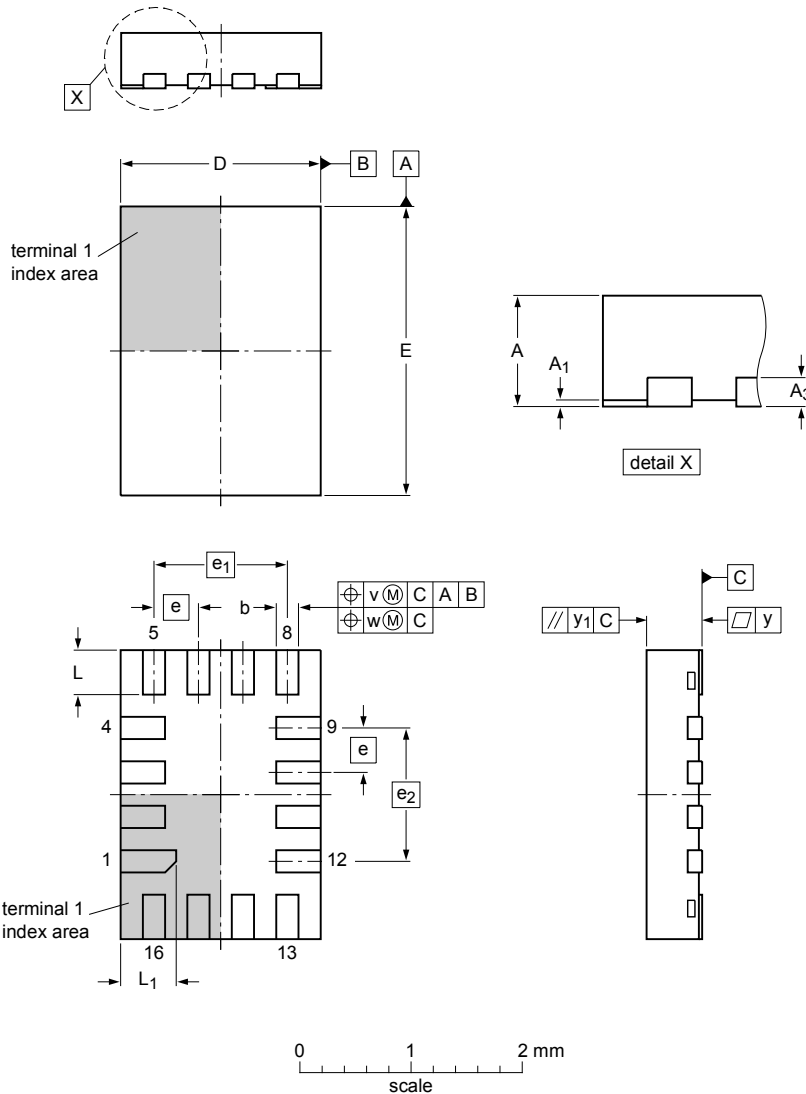


plastic, extremely thin quad flat package; no leads; 16 terminals; body 1.80 x 2.60 x 0.50 mm

2. Package outline

XQFN16: plastic, extremely thin quad flat package; no leads; 16 terminals; body 1.80 x 2.60 x 0.50 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	E	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
max	0.5	0.05		0.25	1.9	2.7				0.45	0.55				
mm nom			0.127	0.20	1.8	2.6	0.4	1.2	1.2	0.40	0.50	0.1	0.05	0.05	0.05
min		0.00		0.15	1.7	2.5				0.35	0.45				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1161-1	---	---	---		09-12-28 09-12-29

Fig. 1. Package outline XQFN16 (SOT1161-1)

3. Soldering

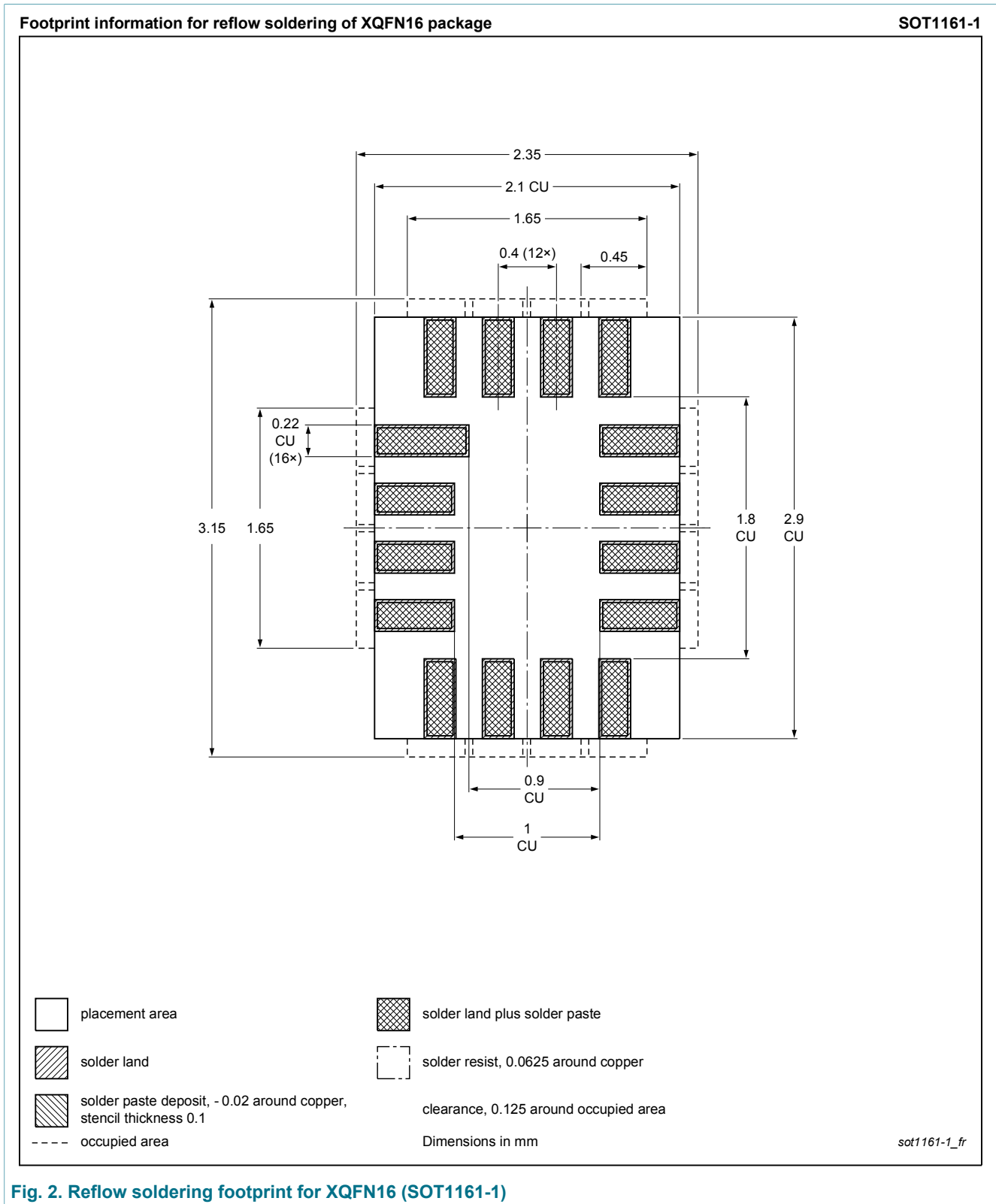


Fig. 2. Reflow soldering footprint for XQFN16 (SOT1161-1)

4. Legal information

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